Icemos Technology Ltd Product Specification 1003.660002 Issue Date 03 October 2023 09:0

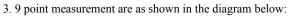
Part Number	Customer	

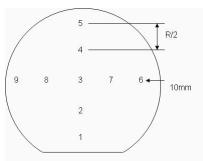
Category	Parameter		Specification	Measurement Method
OverallWafer	1.0	Diameter	150.00 +/- 0.20 mm	
	2.0	Primary Flat Orientation	{110}+/- 1.0 degree	Wafer Vendor
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	none	
	5.0	Overall Thickness	368.00 +/- 5.00 μm	ADE, 100%
	6.0	Total Thickness Variation (TTV)	<1.00μm	ADE, 100%
	7.0	Bow	<30.00μm	ADE to ASTM F534, 20%
	8.0	Warp	<30.00μm	ADE to ASTM F657, 20%
	9.0	Edge Chips	None	Bright Light, 100% (note 2)
	10.0	Edge Exclusion	5mm	
	11.0	Flatness (SBIR)	<1um, 15mm X 15mm. No partials.	
	12.0	Front Surface Quality	Polished. No Particles >10um	
HandleSilicon	13.0	Handle Silicon Raw Material	Prime Silicon	
	14.0	Handle Growth Method	CZ	Wafer Vendor
	15.0	Handle Orientation	{100} +/- 1.0 degree	Wafer Vendor
	16.0	Handle Thickness	368.00 +/- 5.00 μm	ADE, 100%
	17.0	Handle Doping Type	N	Wafer Vendor
	18.0	Handle Dopant	Phosphorous	Wafer Vendor
	19.0	Handle Resistivity	1∼ 3 Ohmem	Wafer Vendor
	20.0	Resistivity variation (within wafer)	<10%	Wafer Vendor
	21.0	Backside Finish	Polished, with lasermarking. Light handling scrtaches.	Guaranteed by process
	22.0	Surface Haze	none	Bright Light, 100% (note 2)

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Part Number		Customer		
Category	Parameter	Specification	Measurement Method	
Shipping Details	Wafer per box :	Max 25		
	Packaging:	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging		
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness		
Explanatory Notes	1. Microscope inspec	ction performed using microscope scan as below. 5x objective.		
	2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall			

Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.





Additional Information